



ICE-LOK™ - THERMALLY ENHANCED WEDGELOCKS

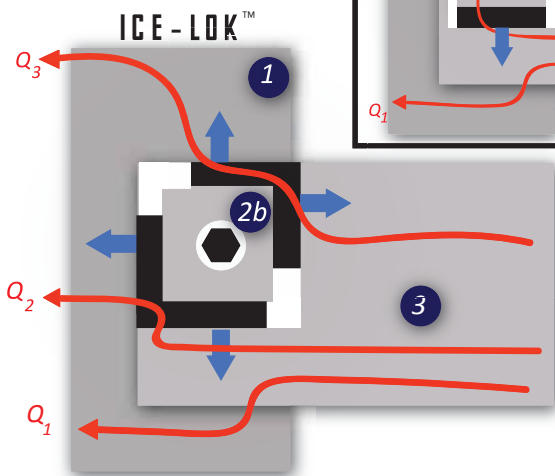
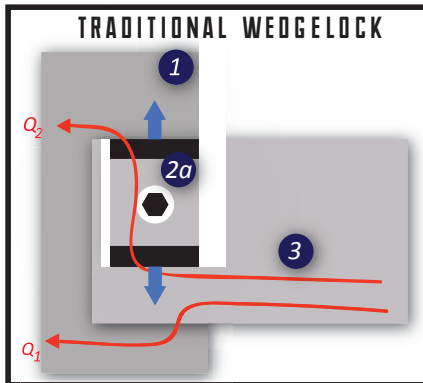
The Isothermal Card Edge (ICE)-Lok™ is designed to enhance thermal performance for conduction cooled embedded computing systems. Compared to conventional wedgelocks, the ICE-Lok™ creates additional heat transfer paths from card to chassis, thereby reducing the thermal resistance (see illustration below). The ICE-Lok™ can be seamlessly integrated into standard VITA systems, creating longer life and higher reliability for your critical components without costly board or chassis redesign.



ICE-LOK™

Benefits

- 33%+ reduction in thermal resistance from equivalent size COTS wedgelocks, due to added heat transfer paths and surfaces
- Single screw access for easy board installation/removal
- Rugged design and construction as validated through shock/vibration testing and repeated installation cycles
- VITA 48.2 compliant. Compatible with standard VITA 3U, 6U and 9U cards
- Superior clamping force

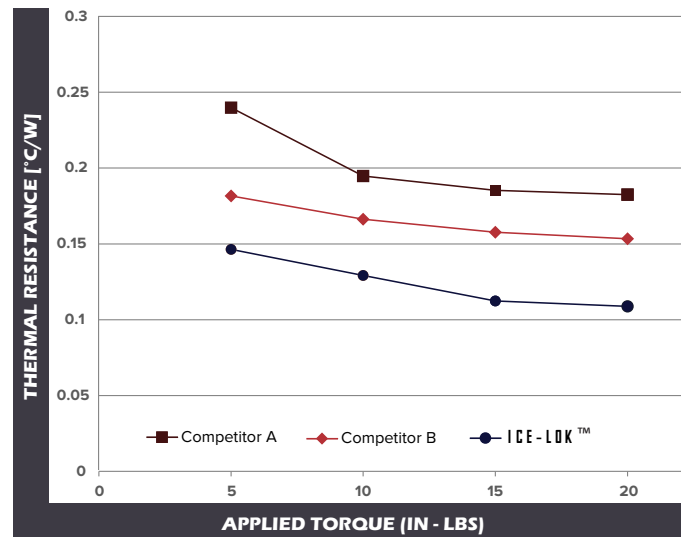


Legend

- 1. Chassis
- 2a. Wedgelock
- 2b. ICE-Lok™
- 3. Card Module
- Heat Flow
- Outward Force

CHASSIS TO CARD TEST RESULTS

ICE-Lok™ results in >10 C° lower component temperature at 100W power input. Utilizing 3/8" ICE-Lok™.



ACT'S ICE-LOK™ SPECIFICATIONS:

Dimensions	VITA compliant for 3/8" and 1/4" cross sections, custom sizes available
Base Material	Aluminum
Finish	Nickel Plated, Anodized, Chem Film, other available upon request
Thermal Resistance	0.13 to 0.15°C/W
Required Torque	Similar to conventional wedgelocks